PLASMA PROCESSING APPARATUS AND PROCESSING METHOD

ABSTRACT

A plasma processing apparatus includes: a processing container configured to be depressurized, a support provided in the processing container and configured to support a workpiece, a heat transfer layer former configured to form, on a placement surface of the support on which the workpiece is placed, a deformable heat transfer layer formed of at least one of a liquid layer or a solid layer for the workpiece, an exhaust line configured to exhaust a processing space in the processing container, and a bypass line that detours the exhaust line, in which the bypass line is provided with a trap configured to retrieve the heat transfer layer in a gas form contained in exhaust from the processing space.

Figure 1